

[54] **LOW PROFILE INTEGRATED CIRCUIT DIP SOCKET**

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[73] Assignee: **Zero Corporation, Burbank, Calif.**

[\*\*] Term: **14 Years**

[21] Appl. No.: **587,394**

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[51] Int. Cl. .... **D13-03**

[52] U.S. Cl. .... **D13/24**

[58] Field of Search ..... **D26/1 R, 1 A, 1 D, 1 E; 339/17 CF, 17 LM, 17 M, 18 R, 18 B, 198 R, 198 G, 176 MP**

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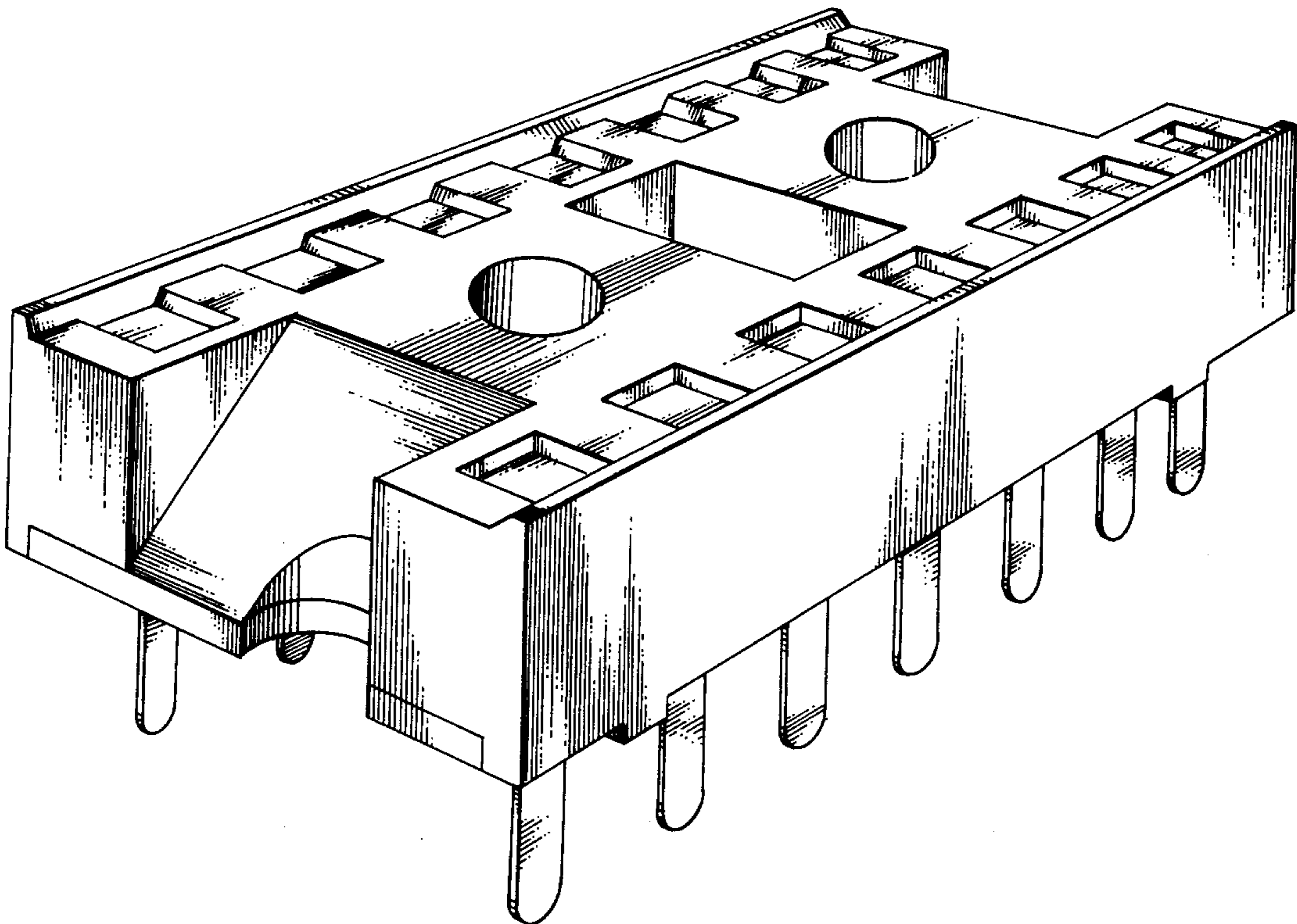
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[57] **CLAIM**

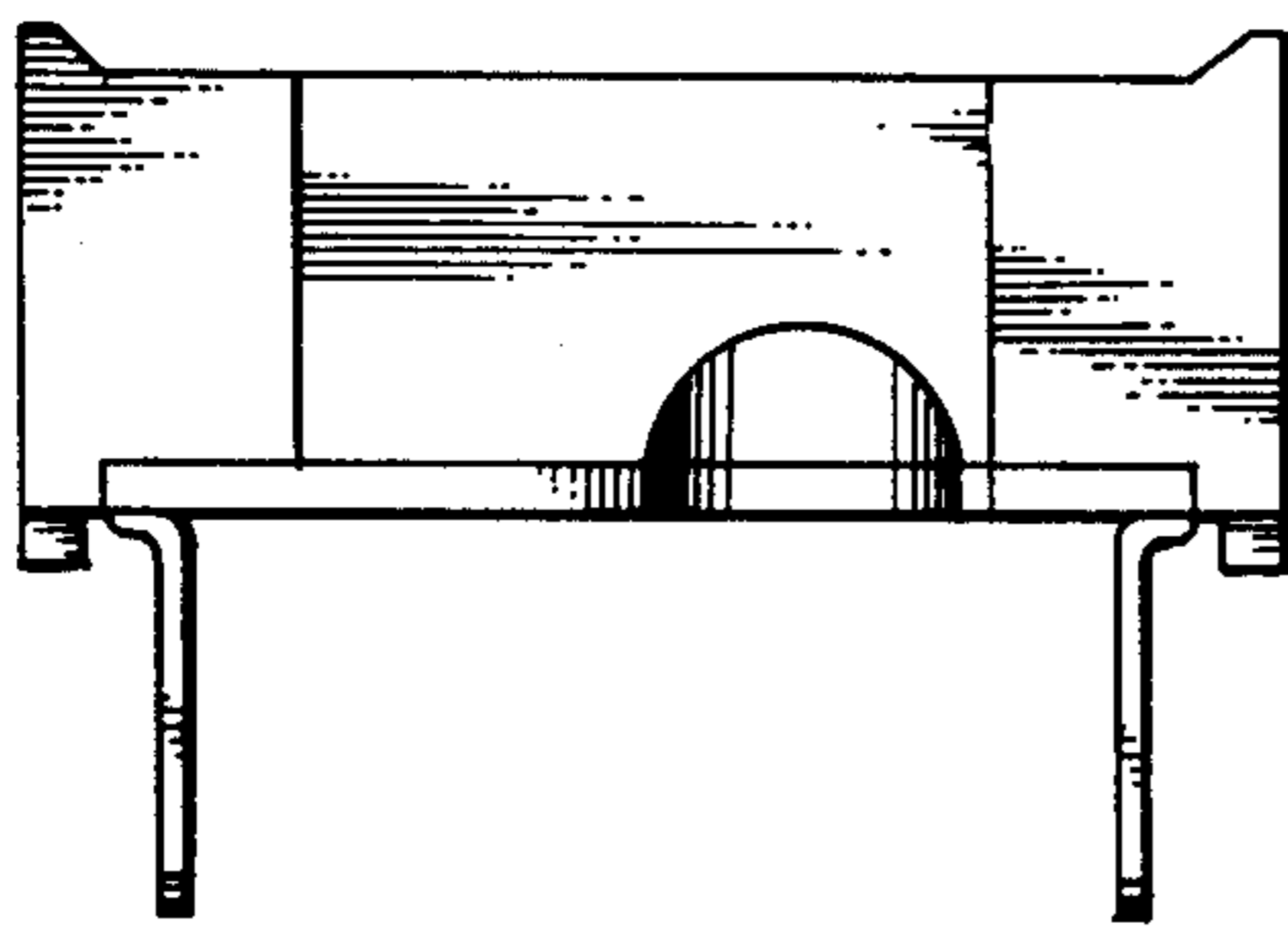
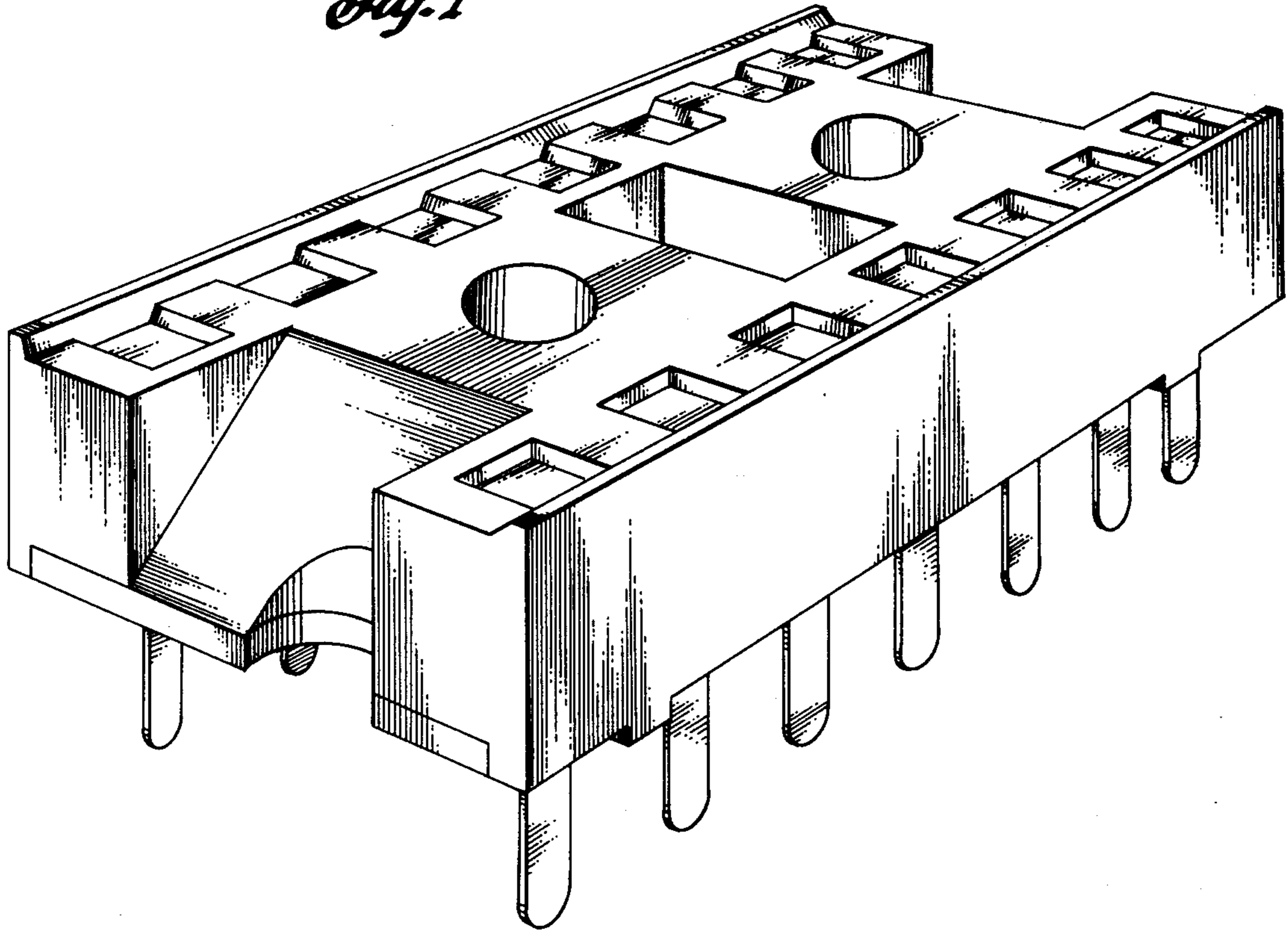
The ornamental design for a low profile integrated circuit dip socket, substantially as shown.

**DESCRIPTION**

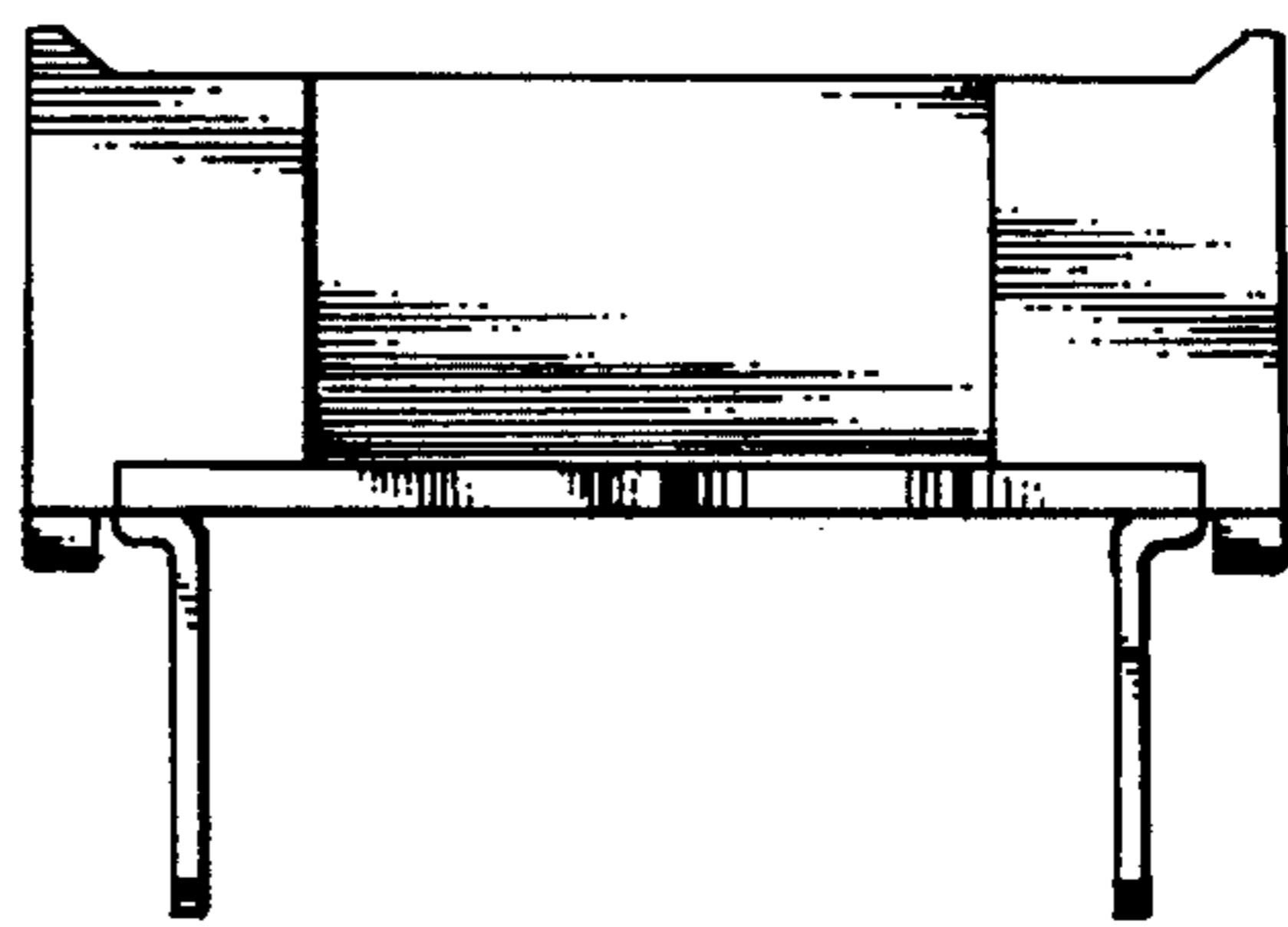
FIG. 1 is a right front perspective view of a low profile integrated circuit socket showing our new design; FIG. 2 is a front end elevational view thereof; FIG. 3 is a rear end elevational view thereof; FIG. 4 is a bottom plan view thereof; FIG. 5 is a right front perspective view of an eight pin socket embodiment thereof; FIG. 6 is a bottom plan view of the socket of FIG. 5; FIG. 7 is a front end elevational view thereof; FIG. 8 is a rear end elevational view thereof; FIG. 9 is a rear perspective view of the socket of FIG. 1; and FIG. 10 is a rear perspective view of the socket of FIG. 5.



*Fig. 1*

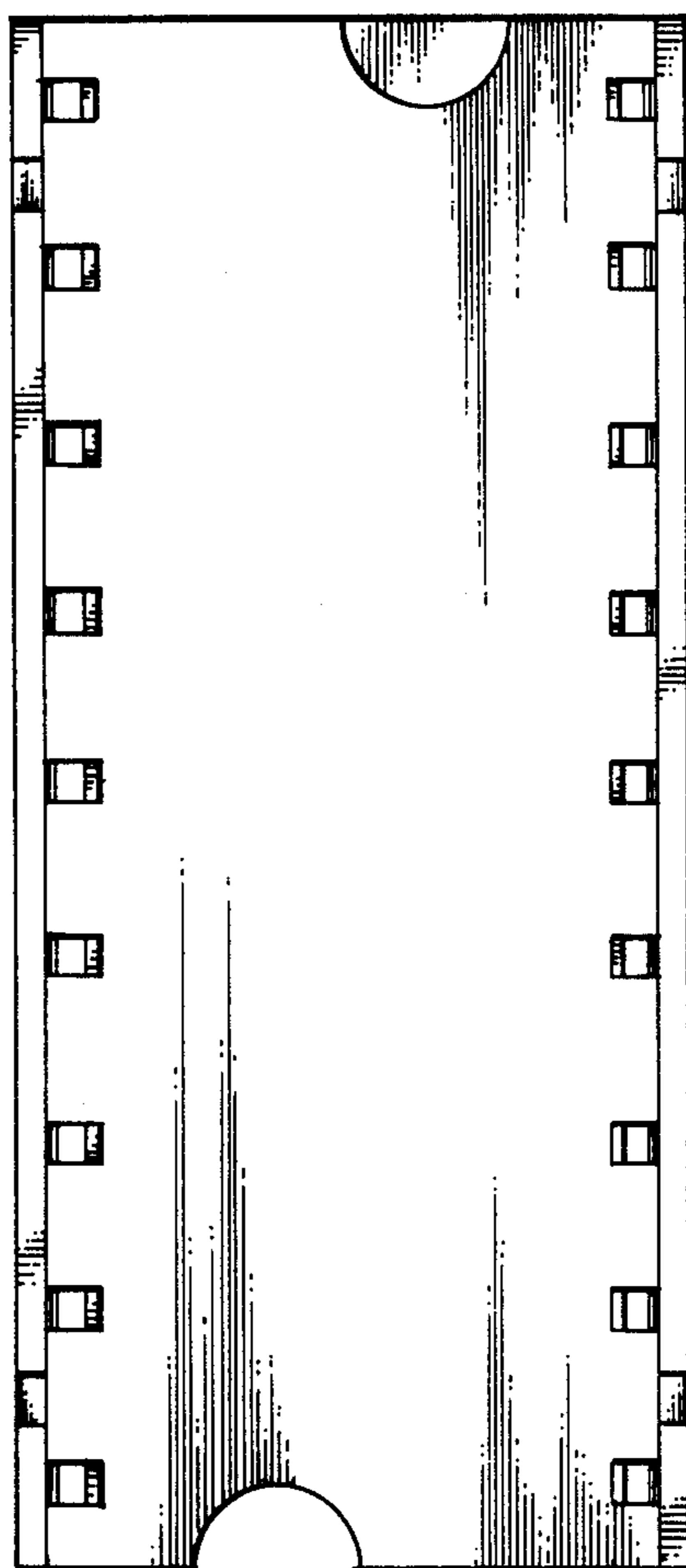


*Fig. 2*

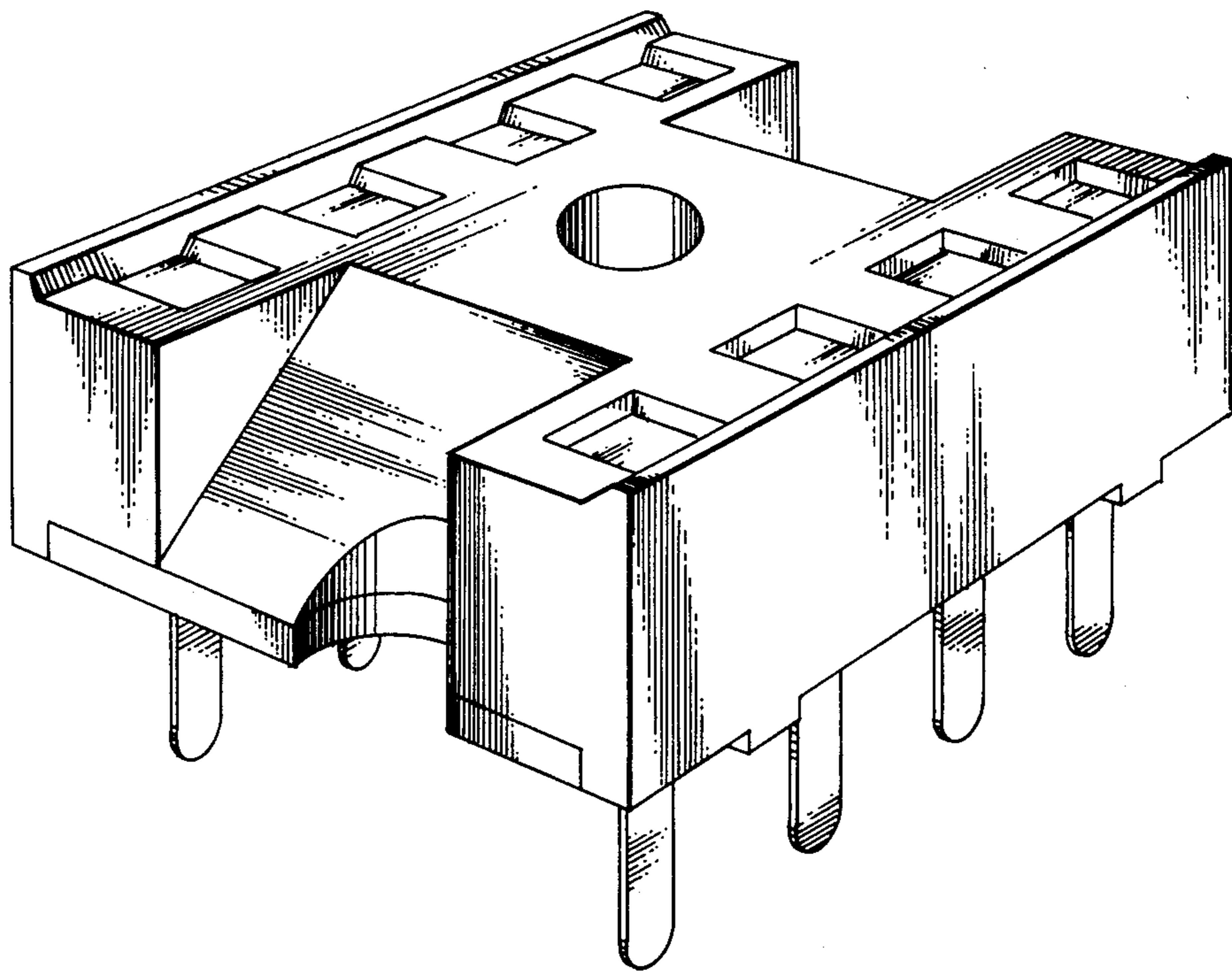


*Fig. 3*

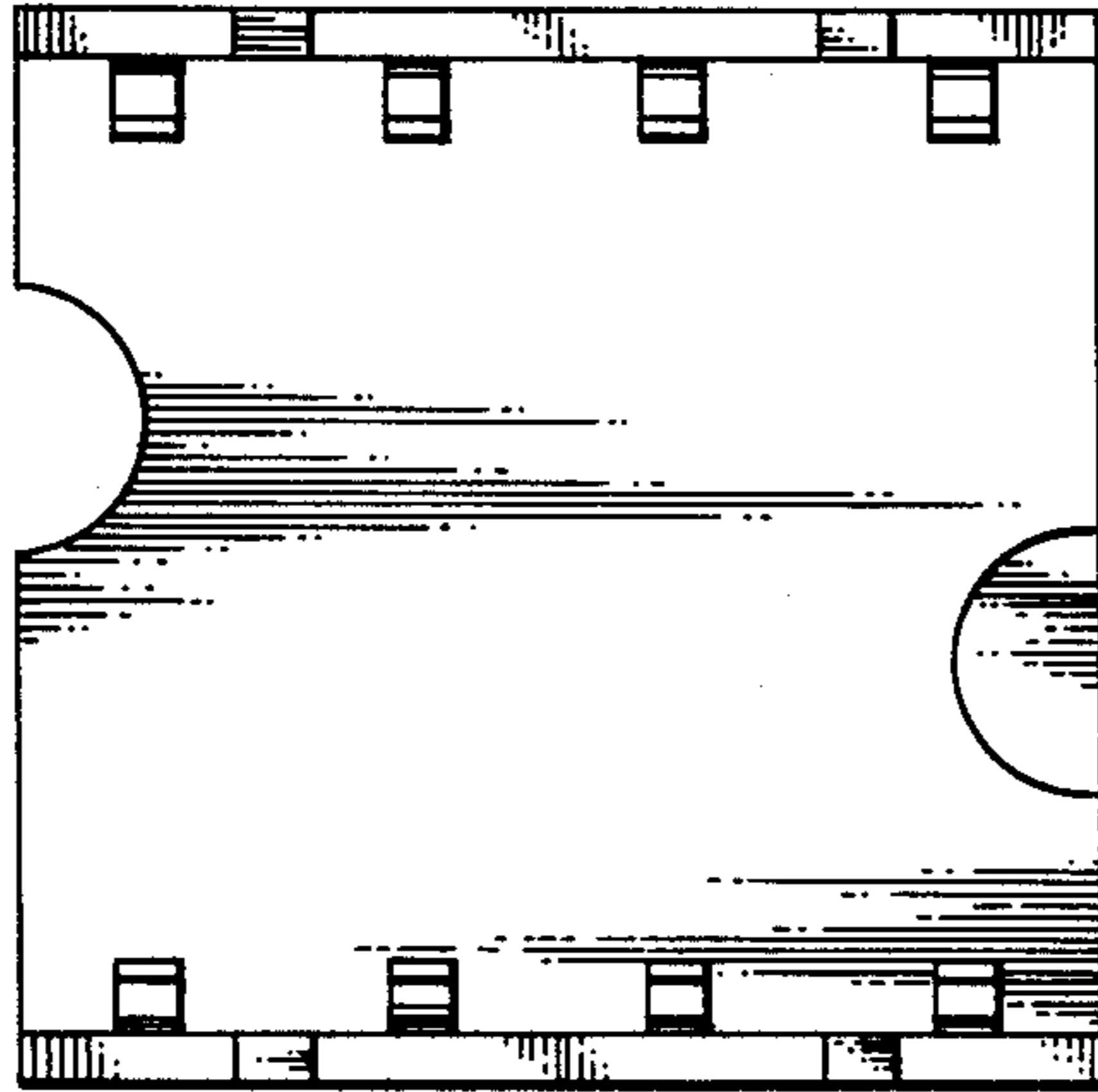
*Fig. 1*



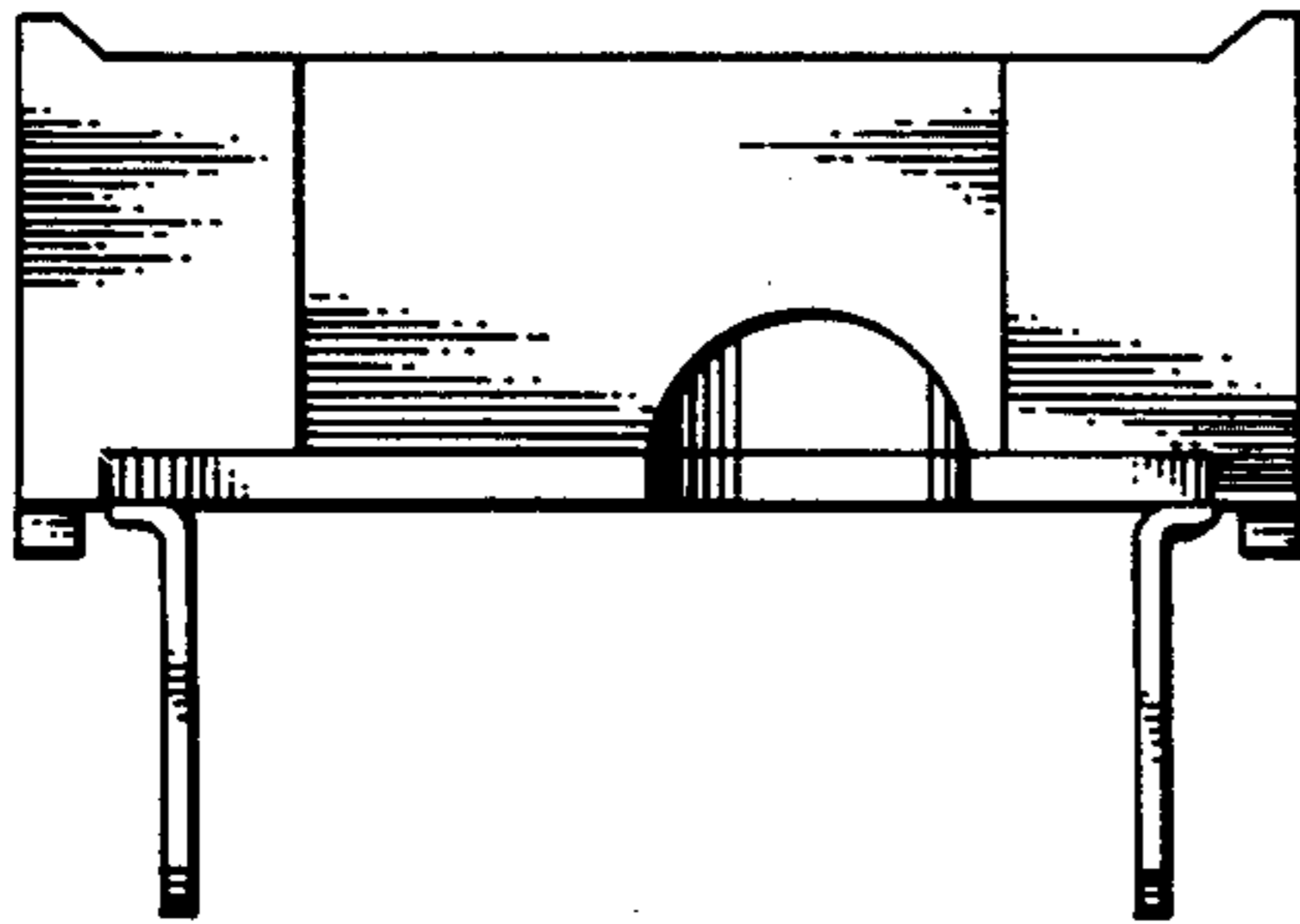
*Fig. 5*



*Fig. 6*



*Fig. 7*



*Fig. 8*

